

MA3ZD120G

Silicon epitaxial planar type

For high speed switching

■ Features

- Forward current (Average) $I_{F(AV)} = 700$ mA rectification is possible
- Low forward voltage: $V_F < 0.45$ V
- High-density mounting is possible

■ Package

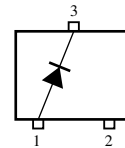
- Code
SMini3-F2
- Pin Name
1: Anode
2: N.C.
3: Cathode

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	20	V
Repetitive peak reverse voltage	V_{RRM}	25	V
Forward current (Average) *1	$I_{F(AV)}$	700	mA
Non-repetitive peak forward surge current *2	I_{FSM}	2	A
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

■ Marking Symbol: M5E

■ Internal Connection



Note) *1: Mounted on an alumina PC board

*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

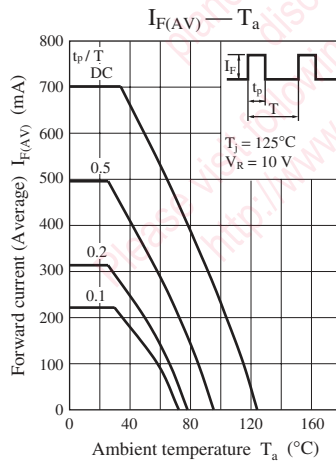
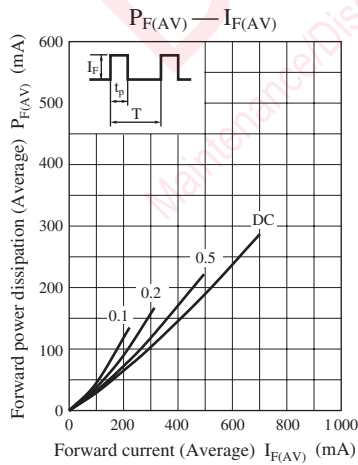
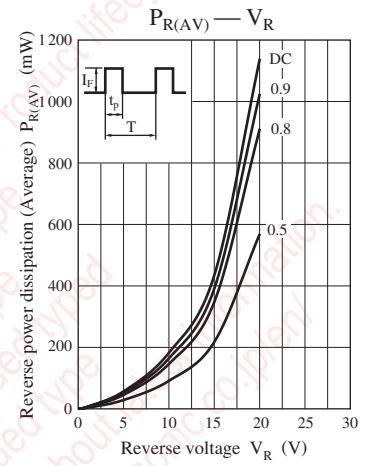
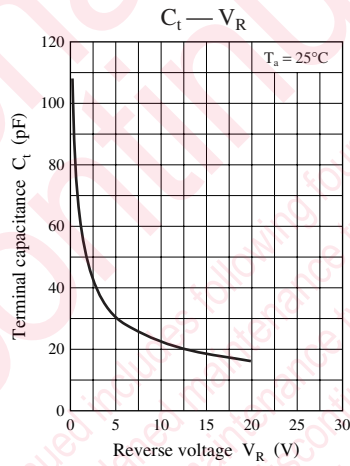
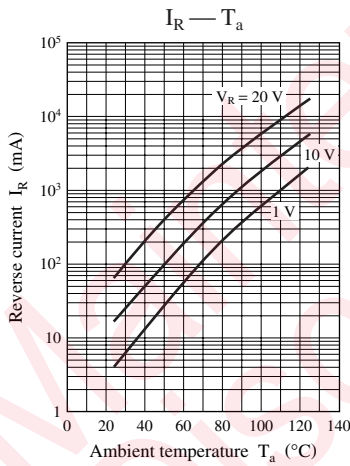
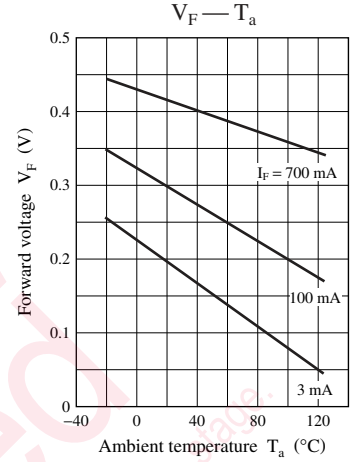
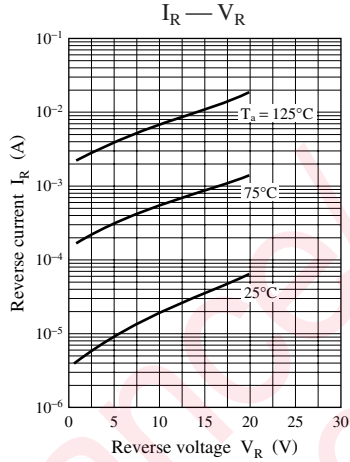
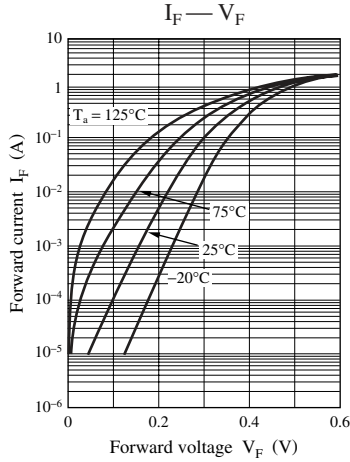
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 700$ mA			0.45	V
Reverse current	I_R	$V_R = 20$ V			200	μA
Terminal capacitance	C_t	$V_R = 0$ V, $f = 1$ MHz		100		pF
Reverse recovery time	t_{rr}	$I_F = I_R = 100$ mA $I_{rr} = 10$ mA, $R_L = 100$ Ω		7		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

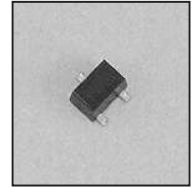
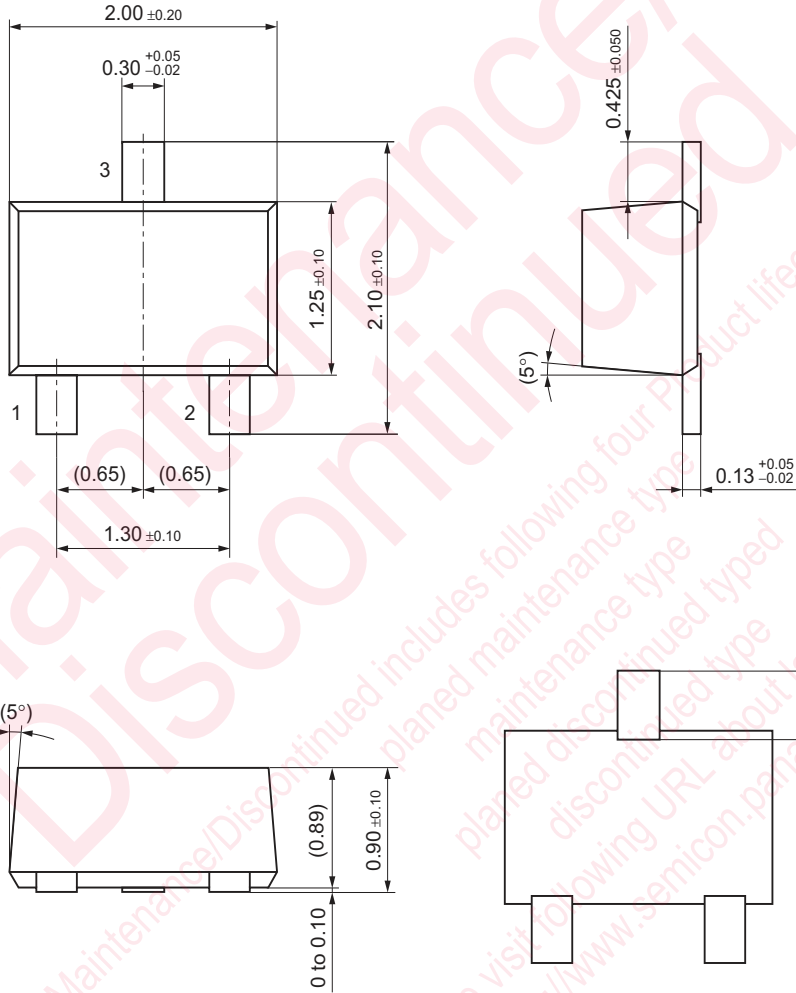
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 250 MHz.



SMini3-F2

Unit: mm



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